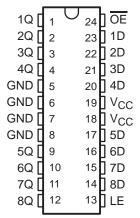
SCAS015B - JUNE 1987 - REVISED APRIL 1996

- Eight Latches in a Single Package
- 3-State Bus Driving True Outputs
- Full Parallel Access for Loading
- Buffered Input and Output-Enable Pins
- Inputs Are TTL-Voltage Compatible
- Flow-Through Architecture Optimizes PCB Layout
- Center-Pin V<sub>CC</sub> and GND Configurations Minimize High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-µm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, and Standard Plastic 300-mil DIPs (NT)

# DB, DW, OR NT PACKAGE (TOP VIEW)



### description

This 8-bit latch features 3-state outputs designed specifically for driving highly-capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight latches of the 74ACT11373 are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When the enable is taken low, the Q outputs are latched at the levels that were set up at the D inputs.

A buffered output-enable  $(\overline{OE})$  input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impendance third state and increased drive provide the capability to drive the bus lines in a bus-organized system without need for interface or pullup components.

OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are off.

The 74ACT11373 is characterized for operation from -40°C to 85°C.

# FUNCTION TABLE (each latch)

	INPUTS	OUTPUT	
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q <sub>0</sub>
Н	Χ	Χ	Z



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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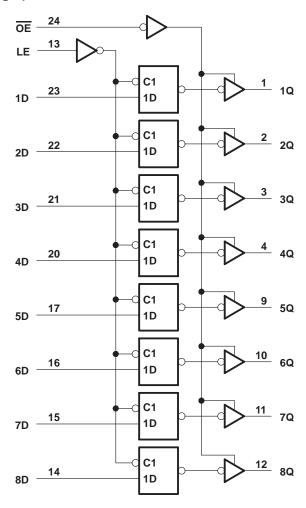
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## logic symbol†

OE LE	13	EN				
LE	23	C1			   1	
1D 2D	22	1D	$\triangleright$	$\nabla$	2	1Q 2Q
3D	21				3	2Q 3Q
4D	17				9	4Q
5D	16				10	5Q
6D 7D	15				11	6Q 7Q
8D	14				12	8Q

<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## logic diagram (positive logic)





## 74ACT11373 OCTAL TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

SCAS015B - JUNE 1987 - REVISED APRIL 1996

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	0.5 V to 6 V
Input voltage range, V <sub>I</sub> (see Note 1)	
Output voltage range, VO (see Note 1)	
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ )	±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±50 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V <sub>CC</sub> or GND	±200 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see	Note 2): DB package 0.65 W
	DW package1.7 W
	NT package1.3 W
Storage temperature range, T <sub>stg</sub>	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150 °C and a board trace length of 750 mils, except for the NT package, which has a trace length of zero.

### recommended operating conditions

		MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
V <sub>IL</sub>	Low-level input voltage		0.8	V
VI	Input voltage	0	VCC	V
Vo	Output voltage	0	VCC	V
IOH	High-level output current		-24	mA
lOL	Low-level output current		24	mA
Δt/Δν	Input transition rise or fall rate	0	10	ns/V
TA	Operating free-air temperature	-40	85	°C



## 74ACT11373 OCTAL TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITION	ie v	v [	Τμ	λ = 25°C	;	MIN	MAX	UNIT
PARAMETER	TEST CONDITION	15 V	vcc	MIN	TYP	MAX	IVIIIV	IVIAA	UNIT
	Jour = 50 A	4	4.5 V	4.4			4.4		
	IOH = -50 μA	5	5.5 V	5.4			5.4		
VOН	I <sub>OH</sub> = -24 mA	4	4.5 V	3.94			3.8		V
	10H = -24 IIIA	5	5.5 V	4.94			4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$						3.85		
	I <sub>OL</sub> = 50 μA	4	4.5 V			0.1		0.1	
	ΙΟΓ = 50 μΑ	5	5.5 V			0.1		0.1	V
V <sub>OL</sub>	I <sub>OL</sub> = 24 mA	4	4.5 V			0.36		0.44	
	10L = 24 111A	5	5.5 V			0.36		0.44	
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5	5.5 V					1.65	
I <sub>OZ</sub>	$V_O = V_{CC}$ or GND	5	5.5 V			±0.5		±5	μΑ
lį	$V_I = V_{CC}$ or GND	5	5.5 V			±0.1		±1	μΑ
ICC	$V_I = V_{CC}$ or GND, $I_O = 0$	5	5.5 V			8		80	μΑ
ΔlCC <sup>‡</sup>	One input at 3.4 V, Other inpu	ts at GND or V <sub>CC</sub> 5	5.5 V			0.9		1	mA
C <sub>i</sub>	$V_I = V_{CC}$ or GND		5 V		4			, and the second	pF
Co	$V_O = V_{CC}$ or GND		5 V		10				pF

<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

# timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		$T_A = 2$	25°C	MIN	MAX	UNIT
		MIN	MAX	IVIIIN	IVIAA	UNIT
t <sub>W</sub>	Pulse duration, LE high	5		5		ns
t <sub>su</sub>	Setup time, data before LE↓	3.5		3.5		ns
th	Hold time, data LE↓	3.5		3.5		ns

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	T,	4 = 25°C	;	MIN	MAX	UNIT
FARAWILTER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	IVIIIV	MAX	ONT
tPLH	D	Q	1.5	7.5	10.3	1.5	11.8	ne
t <sub>PHL</sub>	D	I G	1.5	6.5	9.3	1.5	10	ns
t <sub>PLH</sub>	15	LE Any Q	1.5	8.5	11.3	1.5	13	ns
<sup>t</sup> PHL	LL	Ally Q	1.5	8.5	10.9	1.5	12.2	
<sup>t</sup> PZH	ŌĒ	Any Q	1.5	7	10.7	1.5	12.5	ne
t <sub>PZL</sub>	OE .	Ally Q	1.5	7.5	10.9	1.5	12	ns
<sup>t</sup> PHZ	ŌĒ	Any Q	1.5	10	12.1	1.5	12.2	ne
tPLZ	OE .	Ally Q	1.5	7.5	9.5	1.5	10.1	ns

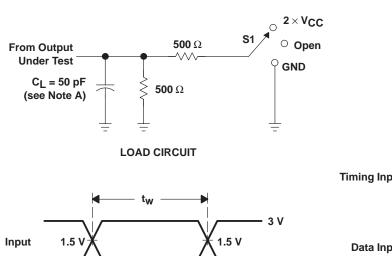


<sup>‡</sup> This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V<sub>CC</sub>.

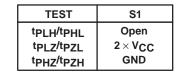
## operating characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

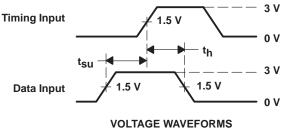
	PARAMETER		TEST CO	TYP	UNIT	
C . Power discinction conscitance nor letch	Outputs enabled	C <sub>1</sub> = 50 pF. f = 1 MHz		65	n.E	
Cpd	Power dissipation capacitance per latch	Outputs disabled	$C_L = 50 \text{ pF},$	1 = 1 IVIDZ	54	рF

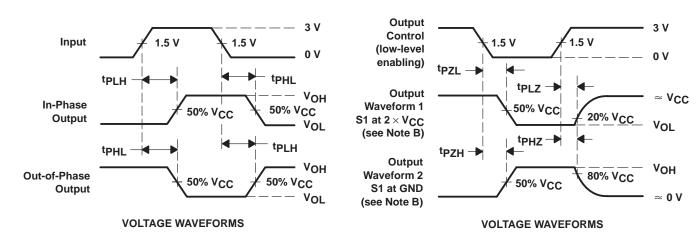
### PARAMETER MEASUREMENT INFORMATION



**VOLTAGE WAVEFORMS** 







NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_\Gamma = 3$  ns.  $t_f = 3$  ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



#### PACKAGE OPTION ADDENDUM

www.ti.com 11-Nov-2009

#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74ACT11373DBLE	OBSOLETE	SSOP	DB	24		TBD	Call TI	Call TI
74ACT11373DBR	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT11373DBRE4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT11373DBRG4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT11373DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT11373DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT11373DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT11373DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT11373DWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT11373DWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT11373NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
74ACT11373NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# **PACKAGE OPTION ADDENDUM**

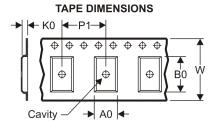
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PACKAGE MATERIALS INFORMATION

www.ti.com 29-Jul-2009

## TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT11373DBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
74ACT11373DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

www.ti.com 29-Jul-2009



Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ACT11373DBR	SSOP	DB	24	2000	346.0	346.0	33.0
74ACT11373DWR	SOIC	DW	24	2000	346.0	346.0	41.0

## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

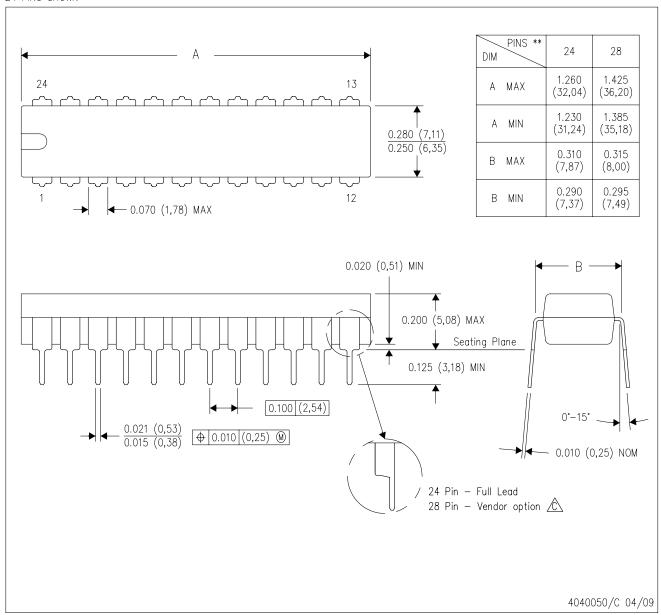
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

# NT (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

The 28 pin end lead shoulder width is a vendor option, either half or full width.



# DW (R-PDSO-G24)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



www.ti.com 30-Apr-2025

#### PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package   Pins	Package qty   Carrier	<b>RoHS</b> (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
74ACT11373DBR	Active	Production	SSOP (DB)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AT373
74ACT11373DW	Obsolete	Production	SOIC (DW)   24	-	-	Call TI	Call TI	-40 to 85	ACT11373
74ACT11373DWR	Active	Production	SOIC (DW)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT11373

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

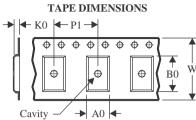
<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

# **PACKAGE MATERIALS INFORMATION**

www.ti.com 16-Apr-2024

### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT11373DBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
74ACT11373DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

www.ti.com 16-Apr-2024



Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ACT11373DBR	SSOP	DB	24	2000	356.0	356.0	35.0
74ACT11373DWR	SOIC	DW	24	2000	350.0	350.0	43.0

DW (R-PDSO-G24)

## PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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